

ABSTRACT OF THE DISCLOSURE

Electronic packages having compliant off-chip interconnects and methods of fabricating compliant off-chip interconnects are disclosed. A representative electronic package includes a substrate and a free-standing compliant off-chip interconnect. The free-standing compliant off-chip interconnect includes a first free-standing arcuate structure that is substantially parallel to the substrate. In addition, the method of fabricating free-standing arcuate structure compliant off-chip interconnects includes: depositing an arcuate structure compliant off-chip interconnect material; and forming the free-standing arcuate structure compliant off-chip interconnect.

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